捷多邦,专业PC**SN54ABT4682**和為**N**54ABT16821 20-BIT BUS-INTERFACE FLIP-FLOPS WITH 3-STATE OUTPUTS

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- Members of the Texas Instruments
 Widebus™ Family
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C
- Distributed V_{CC} and GND Pin Configuration Minimizes High-Speed Switching Noise
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OL})
- Package Options Include Plastic Thin Shrink Small-Outline (DGG), 300-mil Shrink Small-Outline (DL) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package Using 25-mil Center-to-Center Spacings

description

These 20-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing wider buffer registers, I/O ports, bidirectional bus drivers with parity, and working registers.

The 'ABT16821 can be used as two 10-bit flip-flops or one 20-bit flip-flop. The 20 flip-flops are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the device provides true data at the Q outputs.

SN54ABT16821 . . . WD PACKAGE SN74ABT16821 . . . DGG OR DL PACKAGE (TOP VIEW)

10E [1	56]1CLK
1Q1	2	55	1D1
1Q2	3	54] 1D2
GND [4	53	GND
1Q3 [5	52] 1D3
1Q4 [6	51] 1D4
V _{CC} [7	50]v _{cc}
1Q5 [8	49] 1D5
1Q6 [9	48] 1D6
1Q7 [10	47] 1D7
GND [11	46	GND
1Q8 [12	45	1D8
1Q9	13	44	1D9
1Q10 [14	43]1D10
2Q1	15	42	2D1
2Q2 [16	41	2D2
2Q3 [17	40	2D3
GND [18	39	GND
2Q4 [19	38] 2D4
2Q5 [20	37] 2D5
2Q6 [21	36] 2D6
V _{CC} [22	35	Vcc
2Q7 [23	34	2D7
2Q8	24	33	2D8
GND [25	32	GND
2Q9 [26	31] 2D9
2Q10 [27	30	2D10
20E [28	29	2CLK

A buffered output-enable (OE) input can be used to place the ten outputs in either a normal logic state (high or low logic level) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT16821 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT16821 is characterized for operation from –40°C to 85°C.

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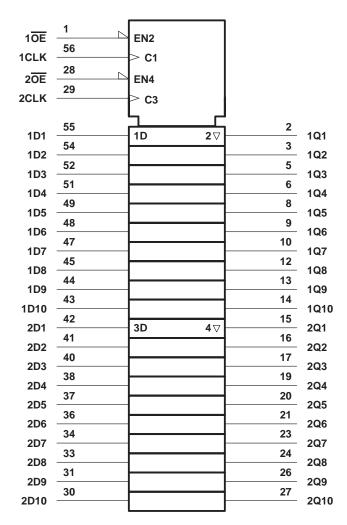


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FUNCTION TABLE (each flip-flop)

	INPUTS	OUTPUT	
OE	CLK	D	Q
L	1	Н	Н
L	\uparrow	L	L
L	L	Χ	Q ₀
Н	X	Χ	Z

logic symbol†

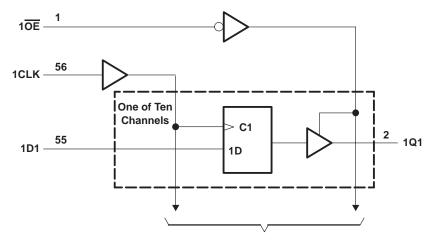


 $^{^\}dagger$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

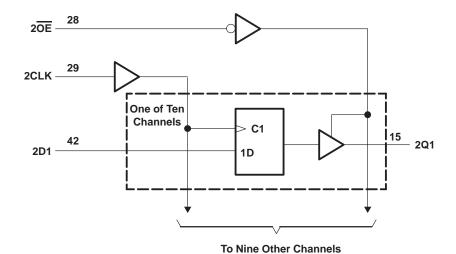


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logic diagram (positive logic)



To Nine Other Channels



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high or power-off state, VO	
Current into any output in the low state, IO: SN54ABT16821	96 mA
SN74ABT16821	128 mA
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current IOK (VO < 0)	
Package thermal impedance, θ _{JA} (see Note 2): DGG package	81°C/W
DL package	
Storage temperature range, T _{stq}	

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51.



NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

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recommended operating conditions (see Note 3)

			SN54ABT	16821	SN74ABT16821		UNIT
			MIN	MAX	MIN	MAX	UNIT
V _{CC} Supply voltage				5.5	4.5	5.5	V
VIH	High-level input voltage		2	FW	2		V
V_{IL}	V _{IL} Low-level input voltage					0.8	V
٧ _I	Input voltage		0 (Vcc	0	VCC	V
IOH	High-level output current		\\ \(\)_	-24		-32	mA
loL	IOL Low-level output current		20	48		64	mA
Δt/Δν	Input transition rise or fall rate	rise or fall rate Outputs enabled		10		10	ns/V
TA	Operating free-air temperature		- 55	125	-40	85	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST CONDITIONS		Т	A = 25°C	;	SN54ABT16821		SN74ABT16821		UNIT		
PARAMETER			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII		
VIK	$V_{CC} = 4.5 V$,	$I_{I} = -18 \text{ mA}$				-1.2		-1.2		-1.2	V	
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$		2.5			2.5		2.5			
Vari	$V_{CC} = 5 V$,	$I_{OH} = -3 \text{ mA}$		3			3		3		\ _\	
Vон	V _{CC} = 4.5 V	I _{OH} = -24 m/	A .	2			2				v	
	VCC = 4.5 V	I _{OH} = -32 m/	A .	2*					2			
Voi	V00 = 45 V	$I_{OL} = 48 \text{ mA}$				0.55		0.55			V	
VOL	$V_{CC} = 4.5 \text{ V}$ $I_{OL} = 64 \text{ mA}$					0.55*				0.55	V	
V _{hys}				100			F			mV		
ΙĮ	$V_{CC} = 5.5 \text{ V}, V_I = V_{CC} \text{ or GND}$				±1		±1		±1	μΑ		
lozh	$V_{CC} = 5.5 \text{ V}, V_{O} = 2.7 \text{ V}$				50	- 4	50		50	μΑ		
lozL	$V_{CC} = 5.5 \text{ V}, V_{O} = 0.5 \text{ V}$				-50	(0)	-50		-50	μΑ		
l _{off}	$V_{CC} = 0$, $V_I \text{ or } V_O \le 4.5 \text{ V}$				±100	² QC			±100	μΑ		
ICEX	$V_{CC} = 5.5 V$,	V _O = 5.5 V	Outputs high			50	Q' Q	50		50	μΑ	
1 ₀ ‡	$V_{CC} = 5.5 V$,	V _O = 2.5 V		-50	-100	-200	-50	-200	-50	-200	mA	
	.,	•	Outputs high			500		500		500	μΑ	
^I CC	$V_{CC} = 5.5 \text{ V}, \text{ I}_{C}$ $V_{I} = V_{CC} \text{ or G}$		Outputs low			89		89		89	mA	
	Al = ACC OLOUP		Outputs disabled			500		500		500	μΑ	
Δl _{CC} §	V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA		
Ci	V _I = 2.5 V or 0.5 V			3.5						pF		
Co	$V_0 = 2.5 \text{ V or } 0$	0.5 V			7.5						pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.



[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

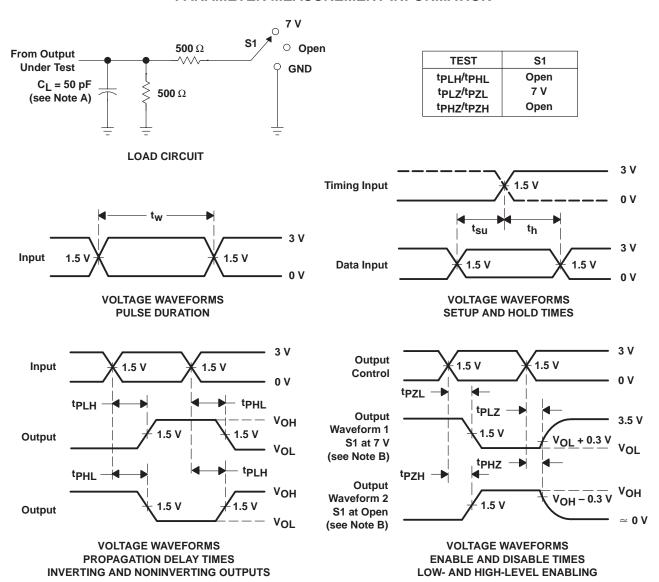
		V _{CC} = 5 V, T _A = 25°C		SN54ABT16821		SN74ABT16821		UNIT
			MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency	0	150	0	150	0	150	MHz
t _W	Pulse duration, CLK high or low	3.3		3.3	10,71	3.3		ns
t _{su}	Setup time, data before CLK↑	1.8		1.8	71.	1.8		ns
th	Hold time, data after CLK↑	1.3		1.3		1.3		ns

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 5 V, T _A = 25°C			SN54ABT16821		SN74ABT16821		UNIT
	(INFOT)	(0011-01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f _{max}			150			150	N.	150		MHz
^t PLH	CLK	Q	1.3	3.7	5.1	1.3	6.7	1.3	6.1	ns
^t PHL		ά	1.6	3.9	5.1	1.6	5.8	1.6	5.4	115
^t PZH	- -	Q	1.1	3.2	4.7	1.1	5.8	1.1	5.7	ns
^t PZL	ŌĒ	Q	1.6	3.8	5	1.6	5.7	1.6	5.6	115
^t PHZ	ŌĒ	Q	2	4.5	5.7	O 2	6.6	2	6.5	no
t _{PLZ}		ά	1.8	4.1	5.8	1.8	8.4	1.8	7.1	ns

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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 $\Omega,\,t_f\leq$ 2.5 ns, $t_f\leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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